

AM62Q-LP STARTER KIT EVM

TABLE OF CONTENTS

PAGE	CONTENTS
01	TABLE OF CONTENTS
02	REVISION HISTORY
03	BLOCK DIAGRAM AM62x SKEVM NAND EXPANSION BOARD
04	X8 NAND I/F
05	ACCESSORIES

PAGE	CONTENTS

REV	E1
VER	1.1



REVISION HISTORY

VER #	DATE	DESCRIPTION OF CHANGES	AUTHOR	REVIEWED BY	APPROVED BY
0.01	18 NOV 2021	Initial Draft	Mistral Design Team		
0.02	07 MAR 2022	Added MCU Mating HDR	Mistral Design Team		
0.03	08 MAR 2022	Removed one MCU MALE HDR	Mistral Design Team		
0.05	11 MAR 2022	Relinked the part J1,J2,J10 with (CRD-081413-A-G-14, CRD-081413-A-G-20, CRD-081413-A-G)	Mistral Design Team		
0.06	14 MAR 2022	Added pull ups for datalines	Mistral Design Team		
0.07	11 APR 2022	Added 4 pin Header for EQEP Encoder, Removed 4 Pin and added 5 pin Header, Also added EQEP Encode	Mistral Design Team		
1.0	13 APR 2022	Rmored 5 Pin HDR and Encoder	Mistral Design Team		
1.1	01 JUN 2022	DNI Property corrected (R1,R4,R5,R6,R9,R19,C1)	Mistral Design Team		

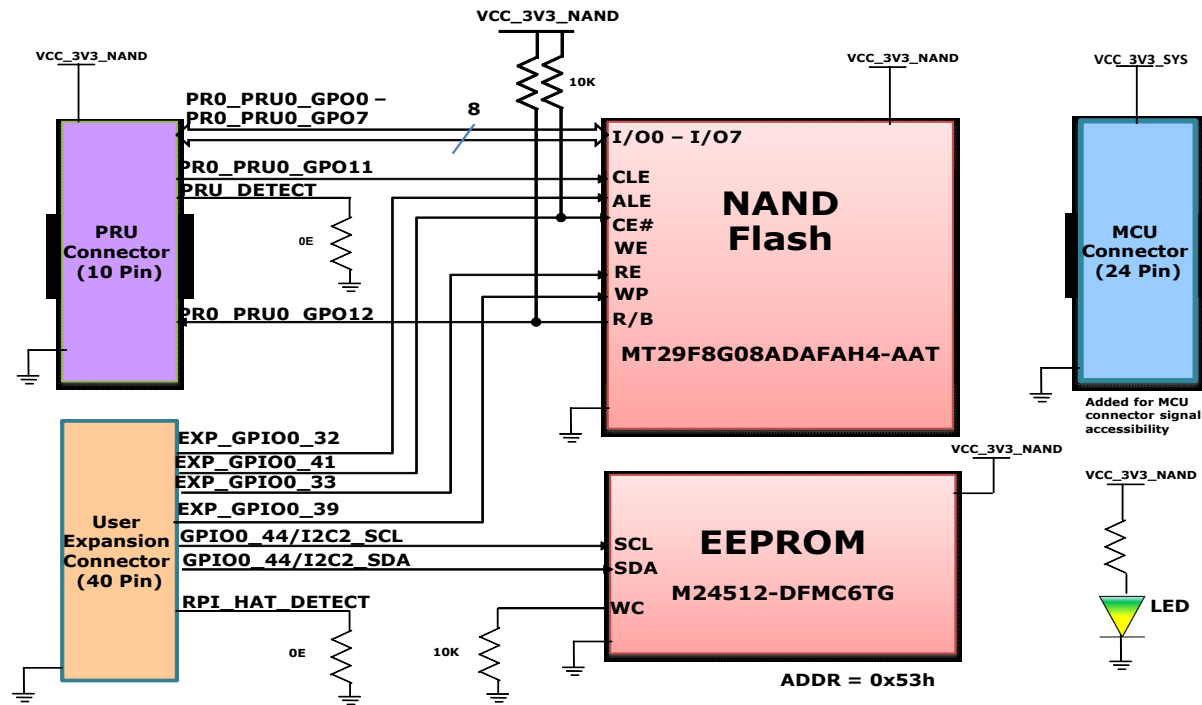
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Title REVISION HISTORY

Size	PROC143E1 x8 NAND EXP CARD	Rev
C		E1
Date:	Wednesday, June 01, 2022	Sheet 2 of 5

BLOCK DIAGRAM AM62Q-LP-SKEVM X8 NAND EXPANSION BOARD



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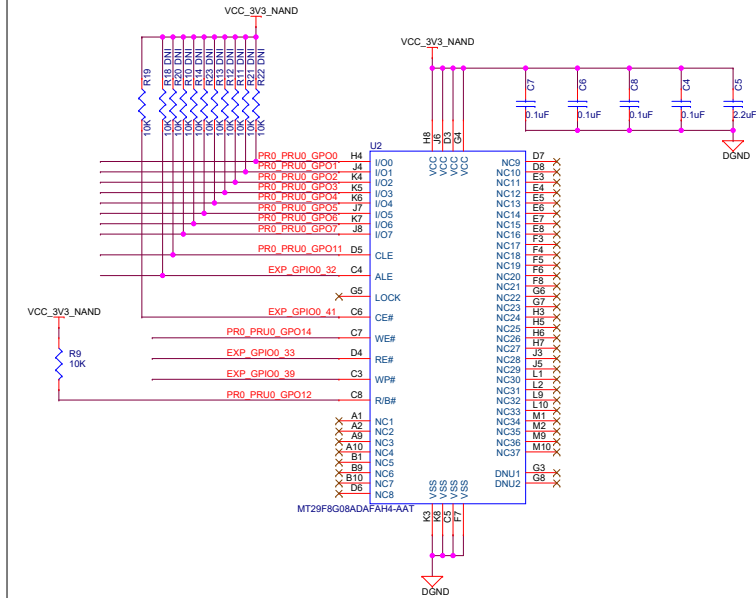


Title BLOCK DIAGRAM x8 NAND

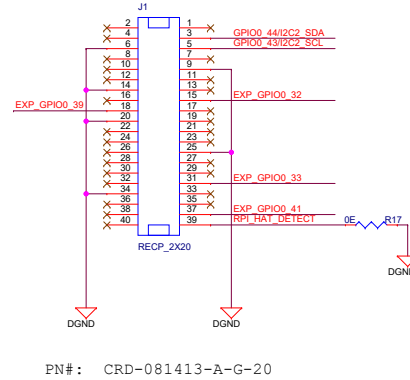
Size	Rev
C	E1
Date: Wednesday, June 01, 2022	Sheet 3 of 5

X8 NAND INTERFACE

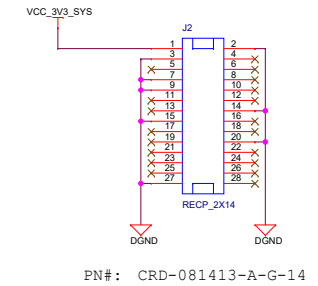
NAND DEVICE



USER EXPANSION CONNECTOR

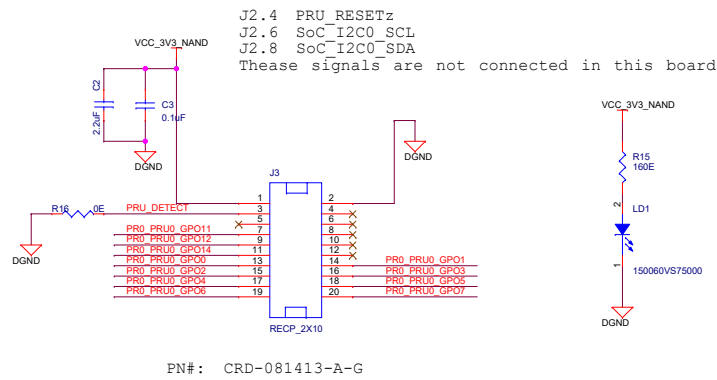


MCU HDR

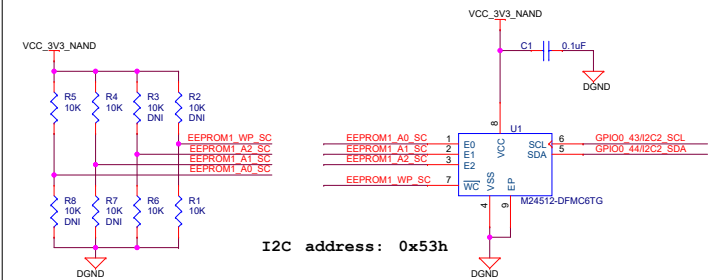


Note: This is used for bringout the MCU HDR Signals from Main board while mounting X8 NAND Expansion card

PRU HEADER



EEPROM



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Title		x8 NAND	
Size	PROC143E1 x8 NAND EXP CARD		Rev
C			E1
Date:	Wednesday, June 15, 2022	Sheet	4 of 5

HARDWARE SCHEMATICS

ASSEMBLY NOTES

- 1. All MSL components should be baked as per JEDEC standard.
- 2. PCB should be baked at 120 degree for 8 hours.
- 3. Board assembly must comply with workmanship standards. IPC-A-610 Class 2, unless otherwise specified.
- 4. These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6. Provide serial numbers to the assembled boards for identification.
- 7. The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

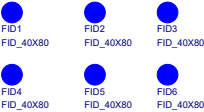
BARE PCB



LOGOs



FIDUCIALS



LABELS

Board Serial No.



Assembly Revision

